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# **Tputty 607 Thermal Reliability**

This report summarizes the thermal reliability testing of Tputty 607. This reliability test procedure is designed to characterize the long term performance of the dispensable thermal gap filler by subjecting the material in the test fixtures to isothermal conditions, repeated thermal shock conditions, and moderate heat and high humidity conditions. The test fixtures feature an isolated sample platform with an area of 12mm x 14mm. Three of these isolated sample platforms are featured on a single test fixture with isolated heating and temperature monitoring for each sample. As an addendum, samples at 1.5mm and 2.2mm were performed in a vertical orientation.

## **Test Equipment**

- Tputty 607, in horizontal positions with a fixed gap of 1.5mm. 1.5mm and 2.2mm in vertical positions as an addendum
- Thermal Shock and Environmental Chambers
- Reliability Test Fixtures
- Power Supply with cartridge heaters
- Data acquisition system for temperature monitoring

# Theory

Thermal resistance of the material is directly proportional to the temperature differential of the surface of the hot plate and the surface of the cold plate (approximating the sample surface temperatures at the substrate interface). The thermal resistance ( $R_{th}$ ) can be represented as the temperature differential ( $\Delta$ T) between the two surfaces for a given heat flow ( $\Delta$ Q).

$$R_{th} = \Delta T /_{\Delta Q}$$



For this procedure, actual thermal resistance is not required as the same sample with test fixture is tested repeatedly. It is sufficient to record the temperature differential and compare the increase or decrease over time to the original performance prior to aging. Thus, the thermal resistance and thermal performance can be inferred from the temperature differential. In essence, an increase in  $\Delta T$  over the reliability testing can be attributed to an increase in thermal resistance of the thermal gap filler.

## **Test Procedure**

#### **Test Fixture and Sample Preparation**

The test fixture is a rectangular fixture with dimensions of approximately 2 inches x 5 inches, or 10 square inches. It consists of an aluminum hot plate and an extruded aluminum heat sink. The hot plate has three machined holes at even intervals for insertion of cartridge heaters. Both hot plate and heat sink have three smaller precision machined holes for thermocouples. The thermocouples can be inserted in very close proximity to the surface of the plates and precisely in alignment for each set of "hot" and "cold" thermocouples. The sample is placed on the 12mmx14mm raised pedestals (0.1mm height) on the hot plate surface and the fixture assembly is fastened by two metal straps. Each test fixture accommodates 3 samples of 12mmx14mm. Final testing gap was set by using metal shims of appropriate height to achieve a sample gap of 1.5mm. During testing, a dual fan unit is placed on top of the aluminum heat sink and air flow is directed from the heat sink to the atmosphere. The completed assembly is operated in an ambient laboratory environment. Once fully assembled, the cartridge heaters are connected to a power supply and power is applied to maintain a hot plate sample temperature of approximately 70°C across the hot plate surface. This is monitored by the data acquisition system. Steady state condition is achieved in approximately forty five minutes to one hour. In the addendum testing, sample gaps of 1.5mm and 2.2mm were achieved using shims. Sample fixtures were placed in the chambers in a vertical orientation and removed every 250 hours, as below, up to 1,000 hours.

Each assembly, with sample, is tested at time zero and then placed into the conditioned chambers for the specified period of time. Generally, every 250 hours the assembly is removed, tested and then placed back into the chamber. Figure 1 shows a detail of the hot plate surface, providing a visual of the isolated and raised sample platform. See figure 2 for an image of the test fixture with dual fan in place for testing.





### Figure 1: Test Fixture Hot Plate Sample Surface



Figure 2: Test Fixture Assembly with Fan



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## Results

### **Thermal Shock**

Thermal shock was performed for 2000 cycles from -40°C to 85°C and for 2000 cycles from -40°C to 125°C. Each cycle is one hour, with the assembly spending thirty minutes at each condition. The sample transition time between the two temperature extremes is approximately 10 seconds. The thermal shock conditions had 1 gap size in a horizontal orientation with 2 test fixtures in each condition. See figures 4 and 5 for thermal shock results. See figure 6 for addendum testing results.

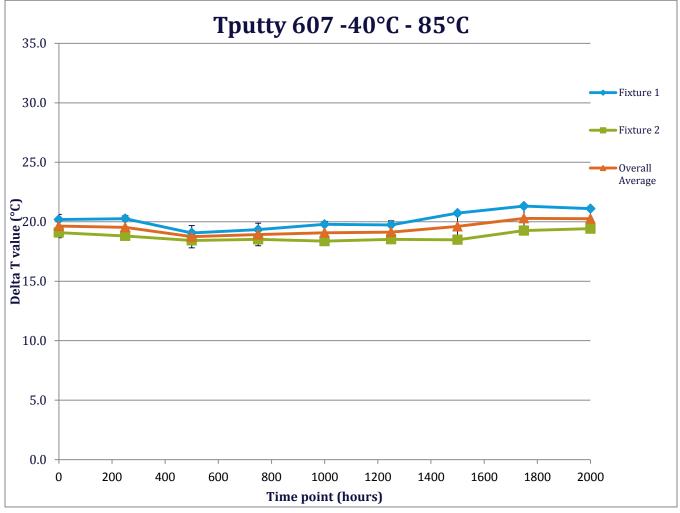


Figure 4: Thermal Shock Results – -40°C to 85°C



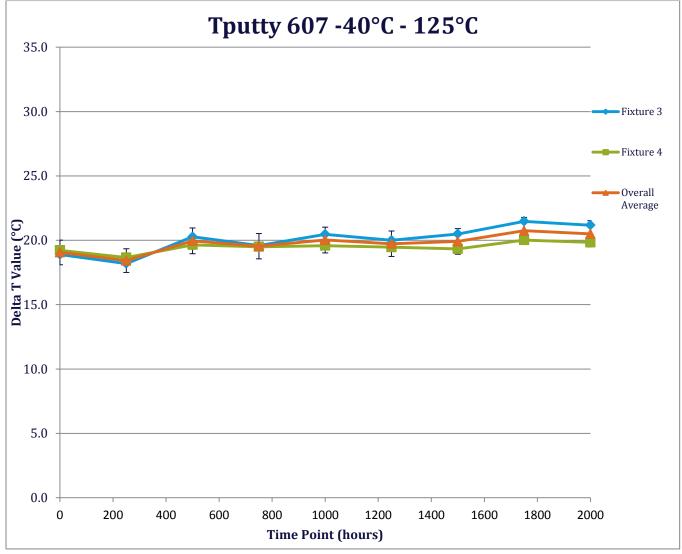


Figure 5: Thermal Shock Results – -40°C to 125°C





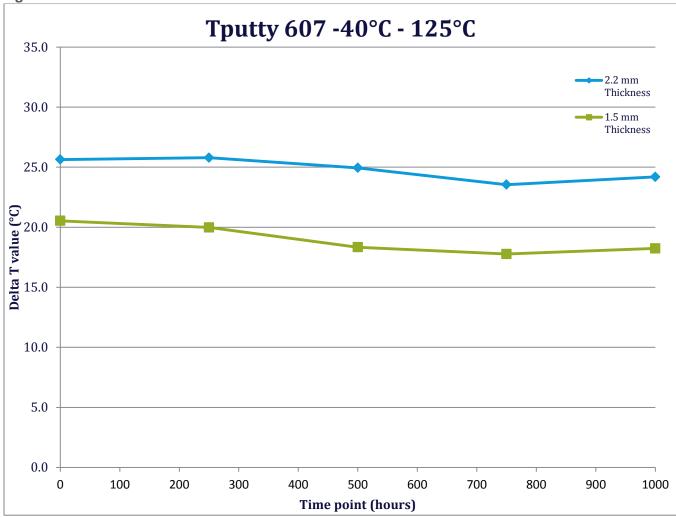


Figure 6: Addendum Thermal Shock Results – -40°C to 125°C in Vertical Orientation

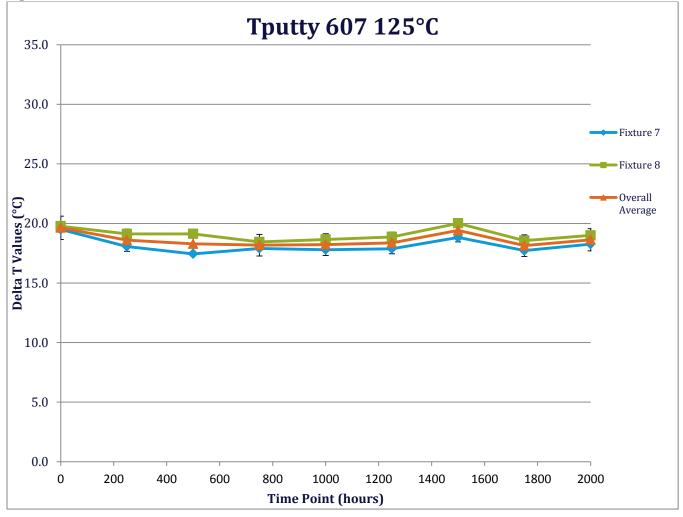
#### **Isothermal Bake**

Isothermal bake was performed for 2000 hours at 125°C and 150°C. The isothermal bake conditions had 1 gap size in a horizontal orientation with 2 test fixtures in each condition. See figures 7 and 8 for isothermal bake results. See figure 9 for addendum testing results.













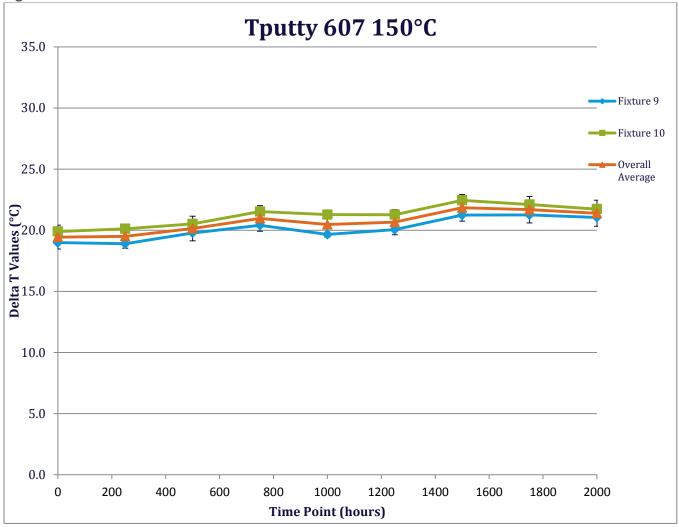


Figure 8: Isothermal Bake Results – 150°C





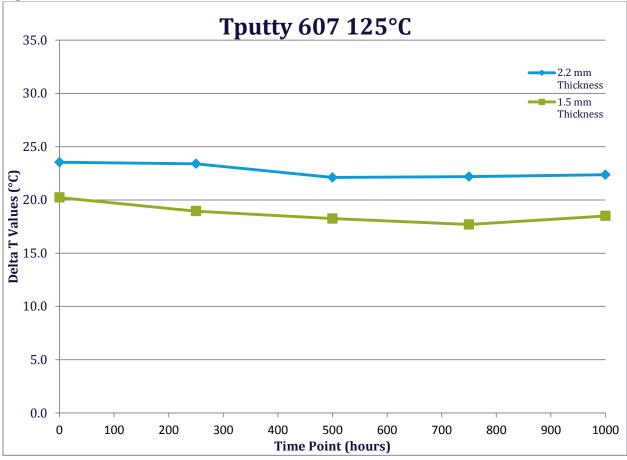


Figure 9: Addendum Isothermal Bake Results – 125°C in Vertical Orientation

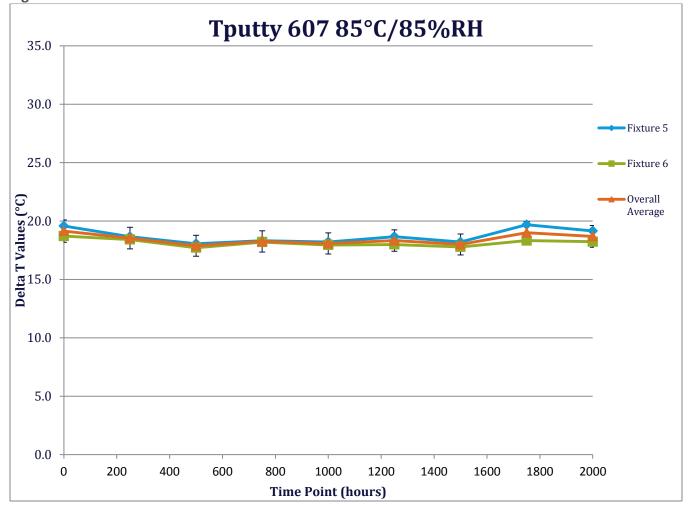
#### HAST

HAST was performed for 2000 hours at 85°C and 85% relative humidity. The HAST condition had 1 gap size in a horizontal orientation with 2 test fixtures each. See figure 10 for HAST results. See figure 11 for addendum results.



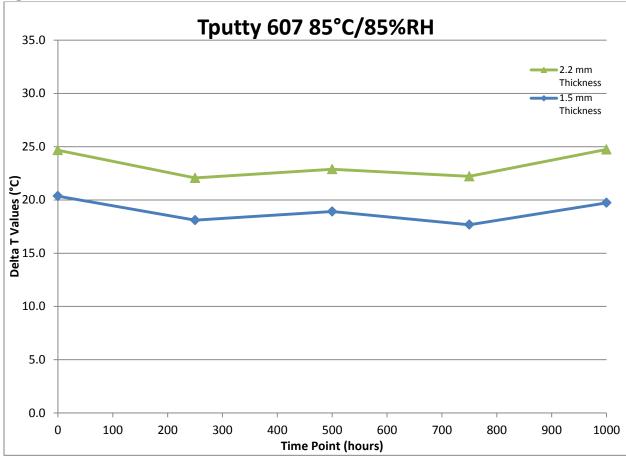


Figure 10: HAST Results











# Conclusion

In conclusion, Tputty 607 showed showed very little change in temperature differential ( $\Delta$ T) in all

aging conditions. This was also demonstrated in the addendum testing in vertical orientation. The material also did not visually slide from the sample gap, and the temperature differential supports this conclusion. The results indicate that the material will be a reliable thermal interface material and will continue to perform well under rigorous conditions similar to those simulated in this report.

## Reported By:

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